

Application No.: 10/691182  
Docket No.: FL0210 US CIP

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**Amendments to Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-19 (Canceled)

20. (New) A process for applying TFE/HFP copolymer to a conductor comprising

- (a) fluorinating TFE/HFP copolymer in an extruder, and
- (b) extruding said TFE/HFP onto a conductor.

21. (New) The process of claim 20, wherein said fluorinating comprises

- (i) melting said fluoropolymer,
- (ii) contacting said molten fluoropolymer with fluorine in isolation from said melting, said contacting being carried out in a reaction zone having free volume,
- (iii) subdividing molten fluoropolymer in said reaction zone to enable said fluorine to effectively contact said molten fluoropolymer so as to carry out the chemical reaction between said fluorine and said molten fluoropolymer,
- (iv) devolatilizing the resultant molten fluoropolymer in isolation from (b) and (c), and
- (v) cooling the devolatilized fluoropolymer.